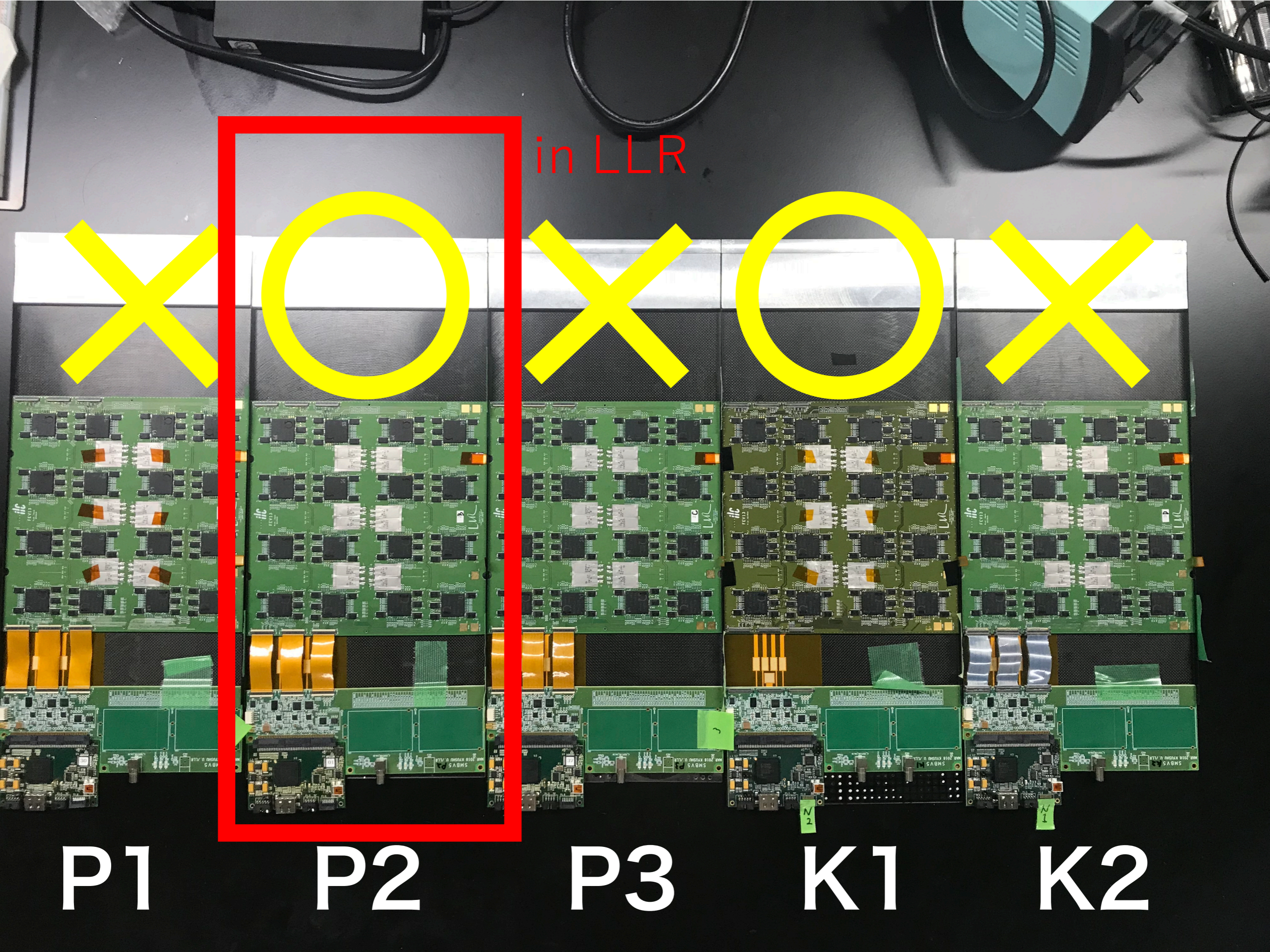# Broken slabs

30/November/2018

Yu Miura

in LLR

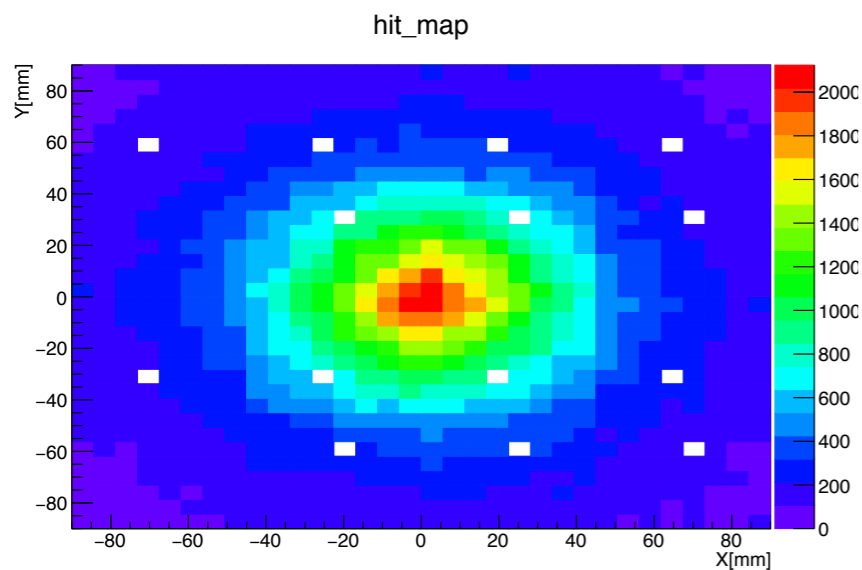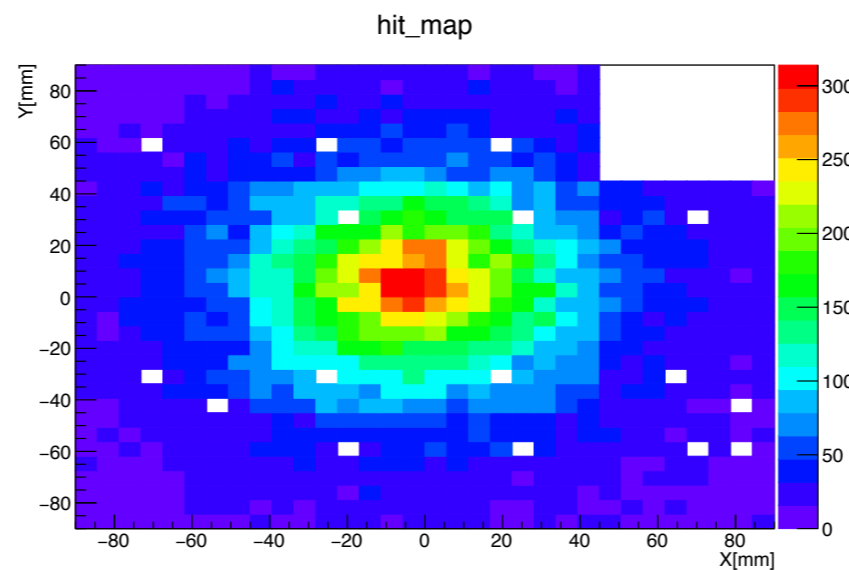P1   P2   P3   K1   K2
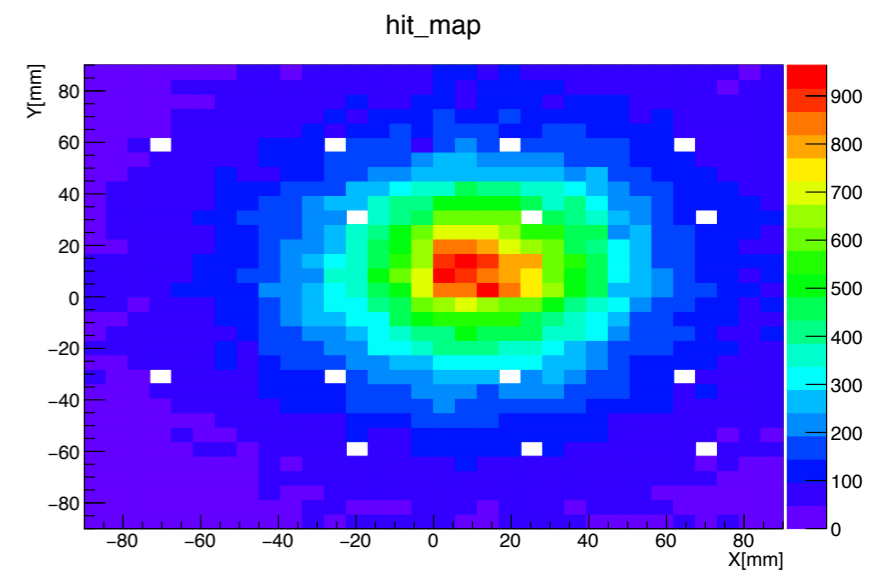
Current condition

- I repaired 3 slabs.

- I checked with ^{133}Ba and create hit maps.
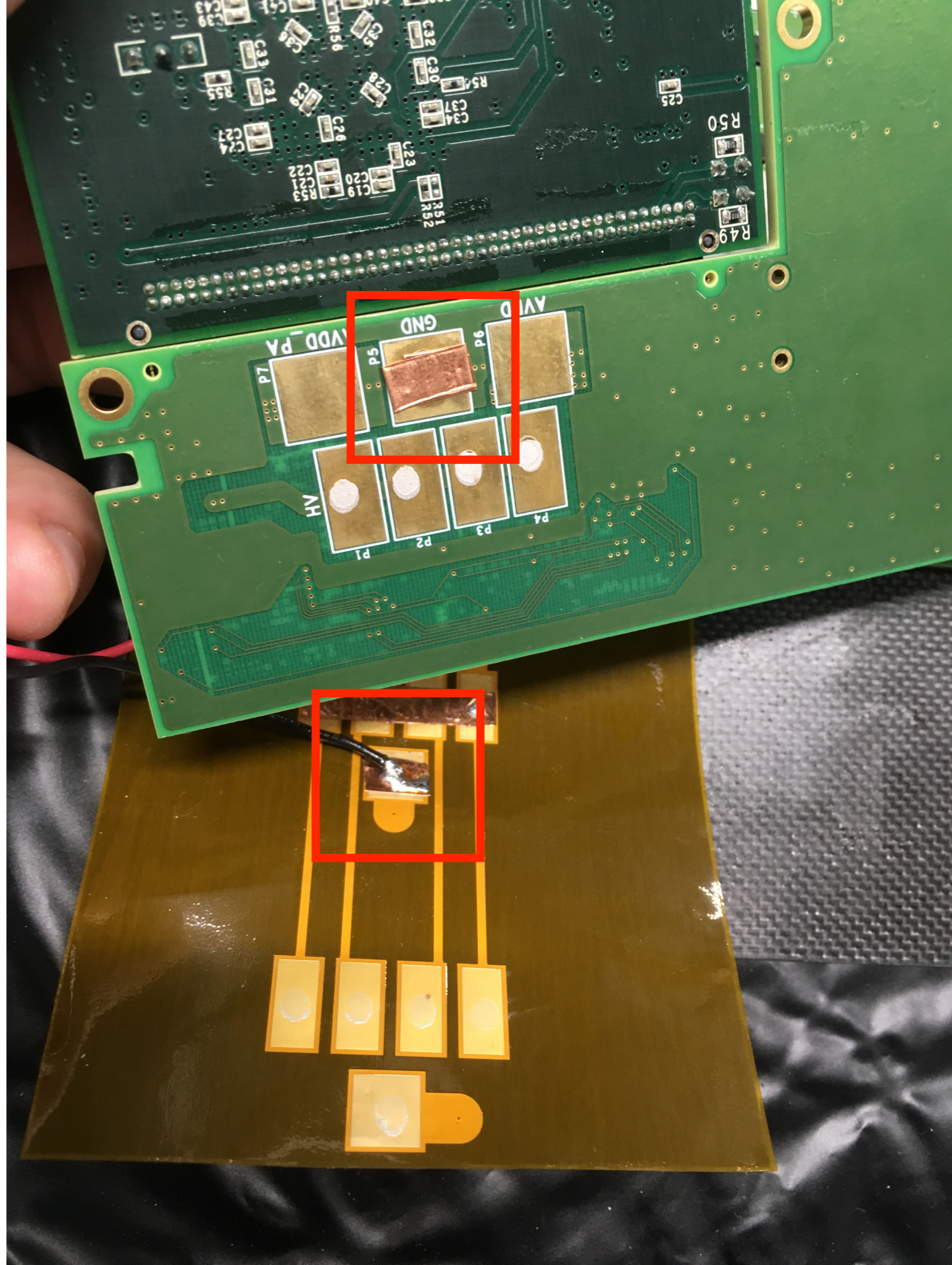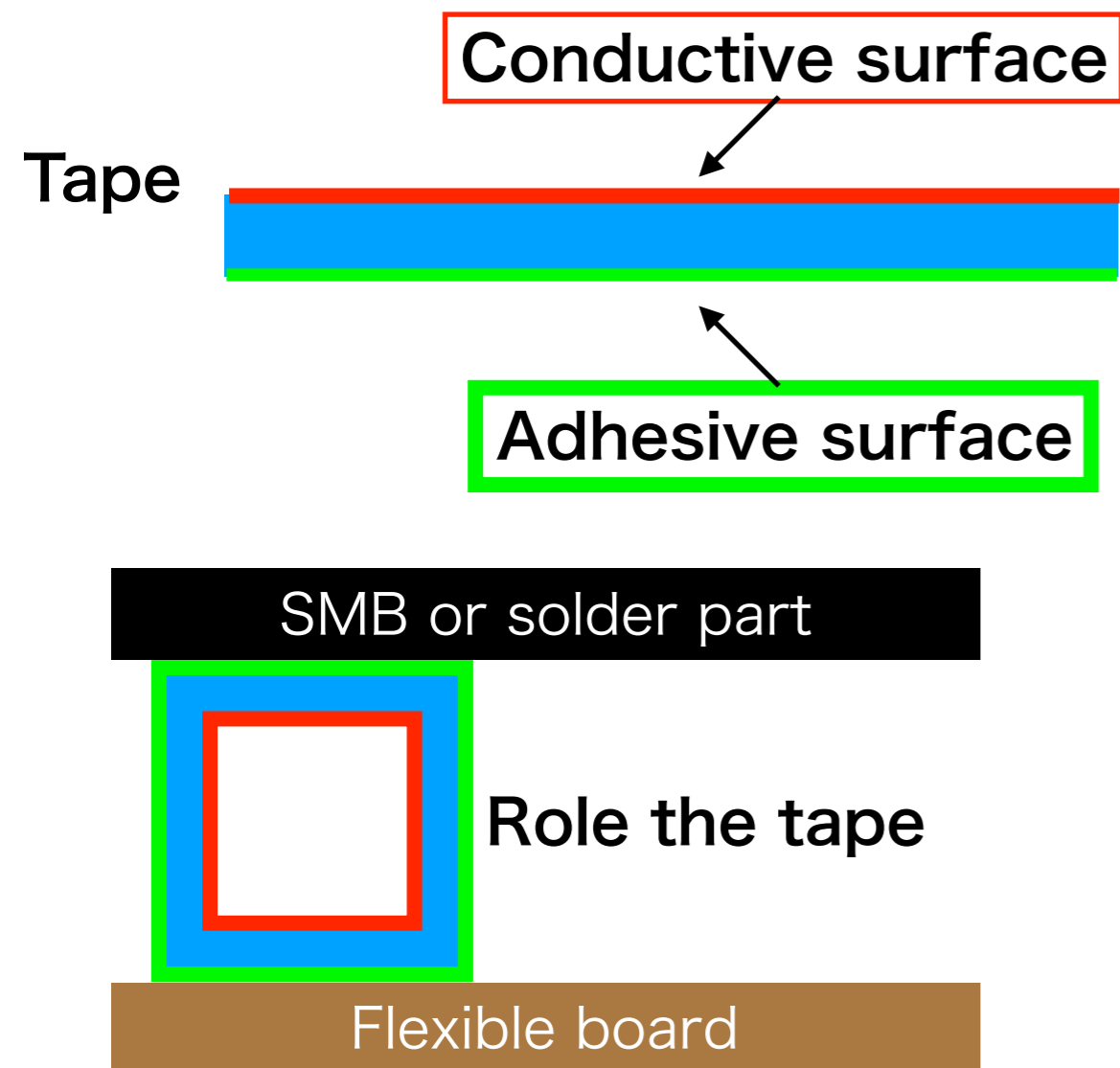 * Chip0 of P3 is very noisy chip because I masked the chip.

P1

P3

K2

Problem (P1)

- We used single side conductive tape.

- Ground was floated.

Tape

Conductive surface

Adhesive surface

SMB or solder part

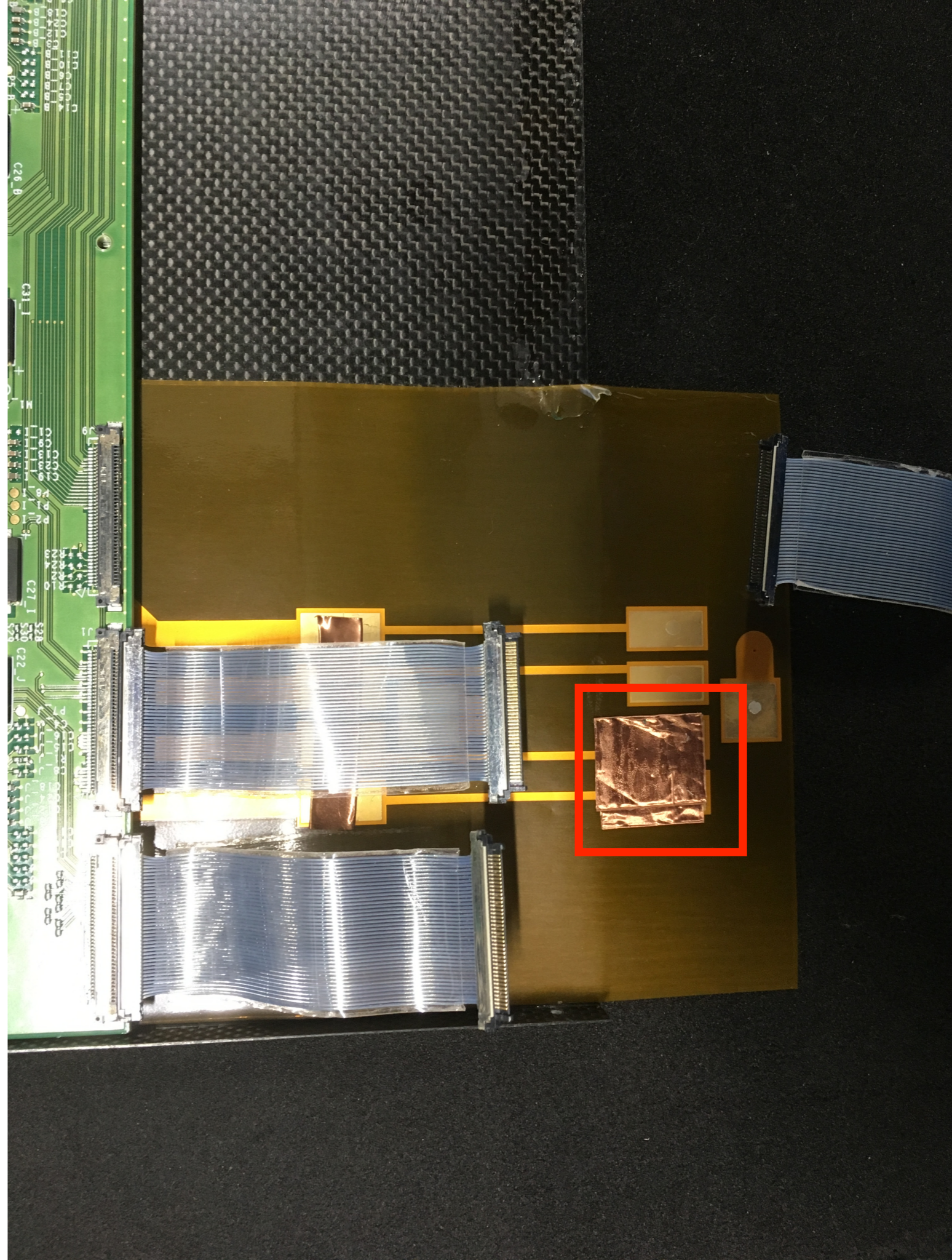Role the tape

Flexible board

Problem (P3)

- Adhesion was peeling

Problem (K2)

- It was similar to P1.

Summary

- Broken slabs are repaired.

- The problem is caused by how to use conductive tape and peeling of the adhesive.